

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT APPLICATION

Applicant : Glenn J. Leedy  
Filed : Concurrently Herewith  
As a Division of  
Application No. : 09/607,363  
Filed : June 30, 2000  
For : THREE DIMENSIONAL STRUCTURE INTEGRATED  
CIRCUIT FABRICATION PROCESS (AS  
AMENDED)

New York, New York 10020  
July 3, 2003

Hon. Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

PRELIMINARY AMENDMENT

Sir:

Preliminary to examination, applicant hereby amends  
the above-identified patent application as follows:

In the Title

Please amend the title from "THREE DIMENSIONAL  
STRUCTURE INTEGRATED CIRCUIT FABRICATION PROCESS" to -- THREE  
DIMENSIONAL STRUCTURE INTEGRATED CIRCUIT --.